

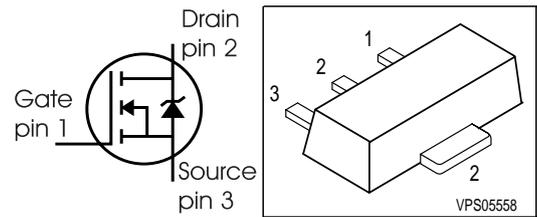
SIPMOS[®] Small-Signal-Transistor

Feature

- N-Channel
- Enhancement mode, Logic Level
- dv/dt rated
- Pb-free lead plating; RoHS compliant
- Qualified according to AEC Q101
- Halogen-free according to IEC 61249-2-21

Product Summary

V_{DS}	240	V
$R_{DS(on)}$	6	Ω
I_D	0.26	A



Type	Package	Pb-free	Tape and Reel Information	Marking
BSS87	P-SOT89-4-2	Yes	H6327: 1000 pcs/reel	KA

Maximum Ratings, at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Continuous drain current $T_A=25\text{ }^\circ\text{C}$ $T_A=70\text{ }^\circ\text{C}$	I_D	0.26 0.21	A
Pulsed drain current $T_A=25\text{ }^\circ\text{C}$	$I_{D\text{ puls}}$	1.04	
Reverse diode dv/dt $I_S=0.26\text{A}$, $V_{DS}=192\text{V}$, $di/dt=200\text{A}/\mu\text{s}$, $T_{jmax}=150\text{ }^\circ\text{C}$	dv/dt	6	kV/ μs
Gate source voltage	V_{GS}	± 20	V
ESD class (JESD22-A114-HBM)		1A (>250V, <500V)	
Power dissipation, related to min. footprint $T_A=25\text{ }^\circ\text{C}$	P_{tot}	1	W
Operating and storage temperature	T_j, T_{stg}	-55... +150	$^\circ\text{C}$
IEC climatic category; DIN IEC 68-1		55/150/56	

Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Thermal resistance, junction - case (Pin 2)	R_{thJC}	-	-	10	K/W
SMD version, device on PCB: @ min. footprint @ 6 cm ² cooling area ¹⁾	R_{thJA}	-	-	125 70	

Electrical Characteristics, at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain-source breakdown voltage $V_{GS}=0, I_D=250\mu\text{A}$	$V_{(BR)DSS}$	240	-	-	V
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D=108\mu\text{A}$	$V_{GS(th)}$	0.8	1.2	1.8	
Zero gate voltage drain current $V_{DS}=240\text{V}, V_{GS}=0, T_j=25^\circ\text{C}$ $V_{DS}=240\text{V}, V_{GS}=0, T_j=150^\circ\text{C}$	I_{DSS}	-	-	0.1 100	μA
Gate-source leakage current $V_{GS}=20\text{V}, V_{DS}=0$	I_{GSS}	-	-	10	
Drain-source on-state resistance $V_{GS}=4.5\text{V}, I_D=0.24\text{A}$	$R_{DS(on)}$	-	4.6	7.5	Ω
Drain-source on-state resistance $V_{GS}=10\text{V}, I_D=0.26\text{A}$	$R_{DS(on)}$	-	3.9	6	

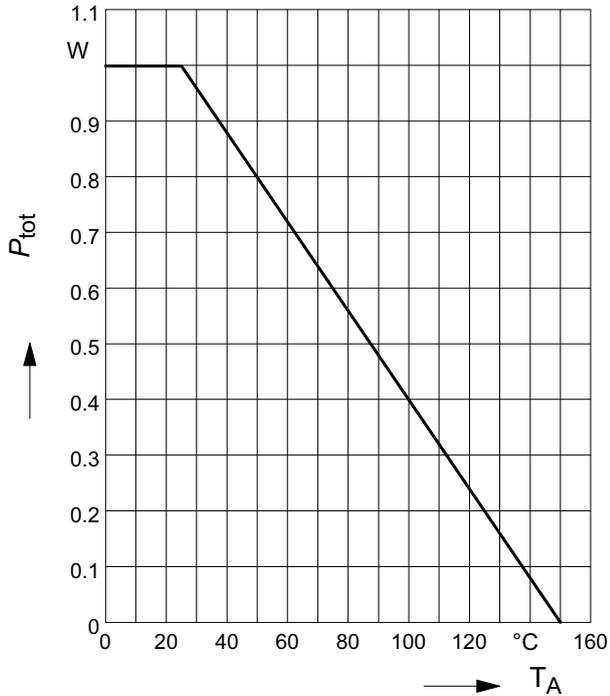
¹⁾Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical without blown air.

Electrical Characteristics, at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic Characteristics						
Transconductance	g_{fs}	$V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$, $I_D = 0.21\text{A}$	0.16	0.33	-	S
Input capacitance	C_{iss}	$V_{GS} = 0$, $V_{DS} = 25\text{V}$,	-	77.5	97	pF
Output capacitance	C_{oss}	$f = 1\text{MHz}$	-	11.2	14	
Reverse transfer capacitance	C_{rss}		-	5.8	7.3	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 120\text{V}$, $V_{GS} = 10\text{V}$,	-	3.7	5.5	ns
Rise time	t_r	$I_D = 0.28\text{A}$, $R_G = 6\Omega$	-	3.5	5.2	
Turn-off delay time	$t_{d(off)}$		-	17.6	26.4	
Fall time	t_f		-	27.3	41	
Gate Charge Characteristics						
Gate to source charge	Q_{gs}	$V_{DD} = 192\text{V}$, $I_D = 0.26\text{A}$	-	0.14	0.21	nC
Gate to drain charge	Q_{gd}		-	1.7	2.5	
Gate charge total	Q_g	$V_{DD} = 192\text{V}$, $I_D = 0.26\text{A}$, $V_{GS} = 0$ to 10V	-	3.7	5.5	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} = 192\text{V}$, $I_D = 0.26\text{A}$	-	2.7	-	V
Reverse Diode						
Inverse diode continuous forward current	I_S	$T_A = 25\text{ }^\circ\text{C}$	-	-	0.26	A
Inv. diode direct current, pulsed	I_{SM}		-	-	1.04	
Inverse diode forward voltage	V_{SD}	$V_{GS} = 0$, $I_F = I_S$	-	0.82	1.2	V
Reverse recovery time	t_{rr}	$V_R = 120\text{V}$, $I_F = I_S$,	-	53.6	80.4	ns
Reverse recovery charge	Q_{rr}	$di_F/dt = 100\text{A}/\mu\text{s}$	-	101	152	

1 Power dissipation

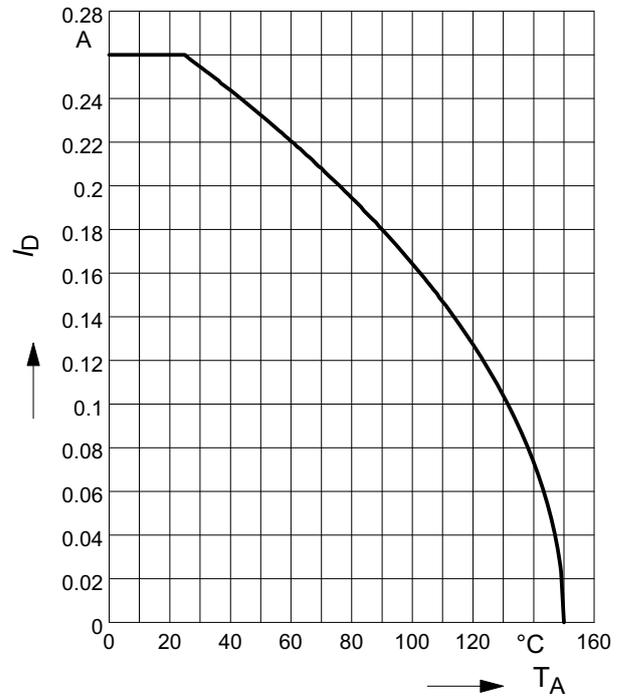
$$P_{tot} = f(T_A)$$



2 Drain current

$$I_D = f(T_A)$$

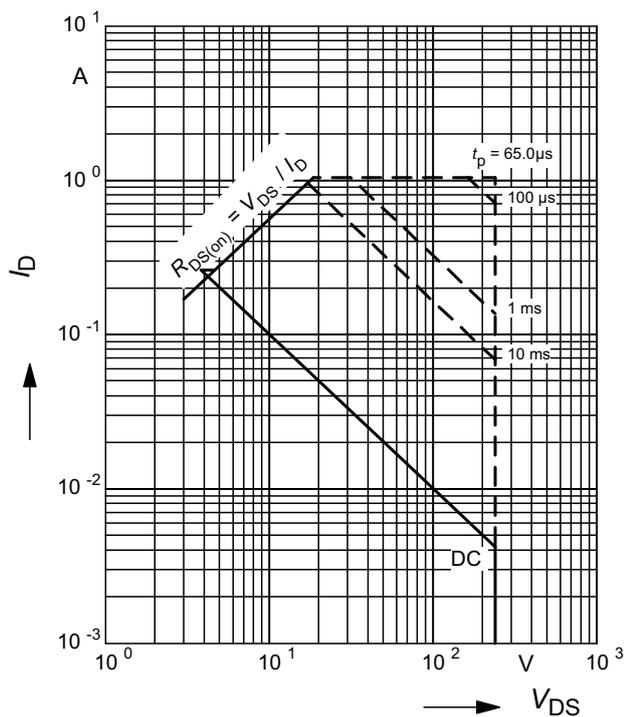
parameter: $V_{GS} \geq 10 \text{ V}$



3 Safe operating area

$$I_D = f(V_{DS})$$

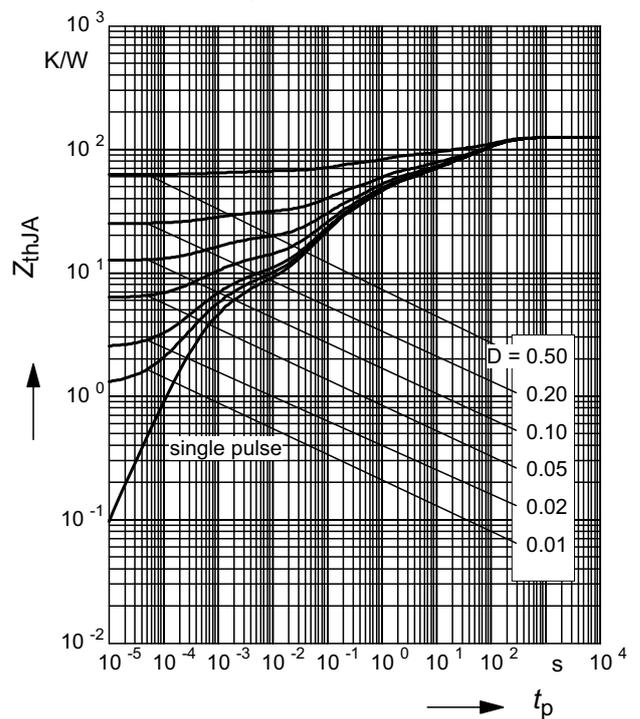
parameter: $D = 0, T_A = 25 \text{ °C}$



4 Transient thermal impedance

$$Z_{thJA} = f(t_p)$$

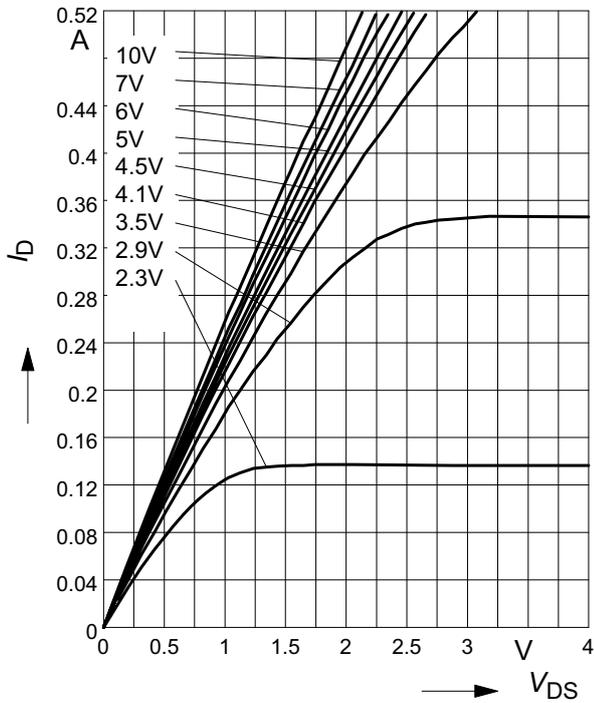
parameter: $D = t_p/T$



5 Typ. output characteristic

$$I_D = f(V_{DS})$$

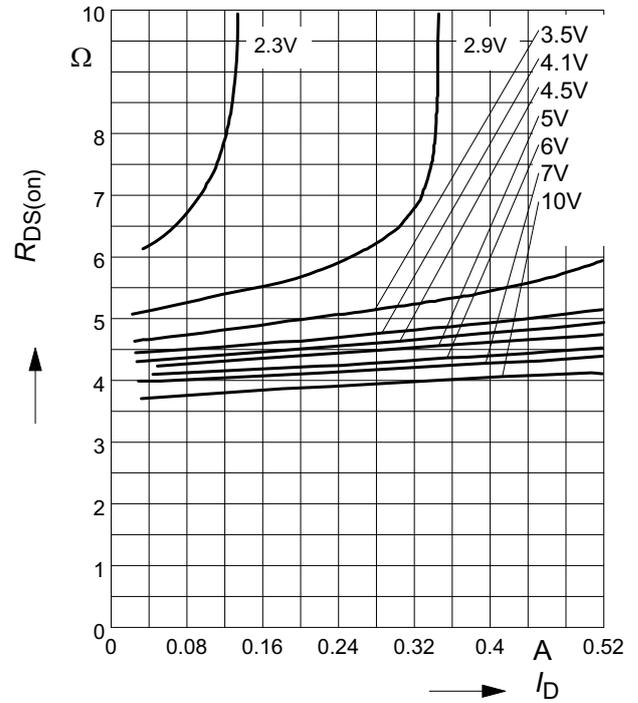
parameter: $T_j = 25\text{ }^\circ\text{C}$, V_{GS}



6 Typ. drain-source on resistance

$$R_{DS(on)} = f(I_D)$$

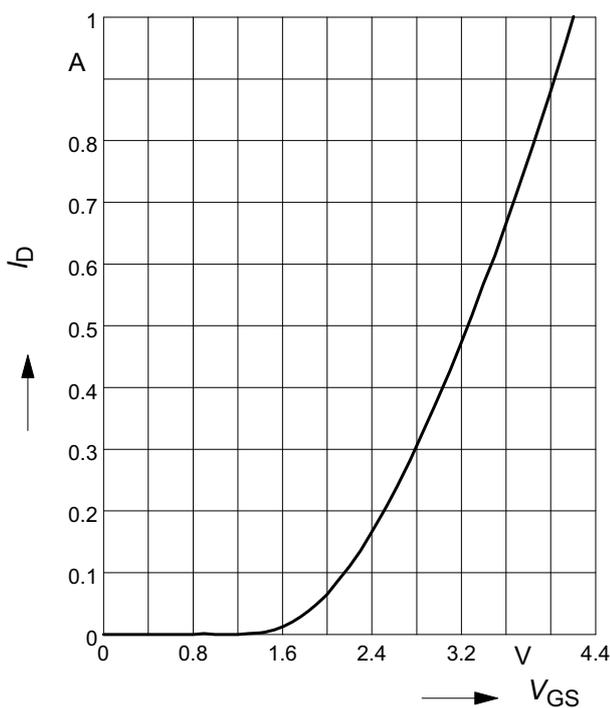
parameter: $T_j = 25\text{ }^\circ\text{C}$, V_{GS}



7 Typ. transfer characteristics

$$I_D = f(V_{GS}); V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$$

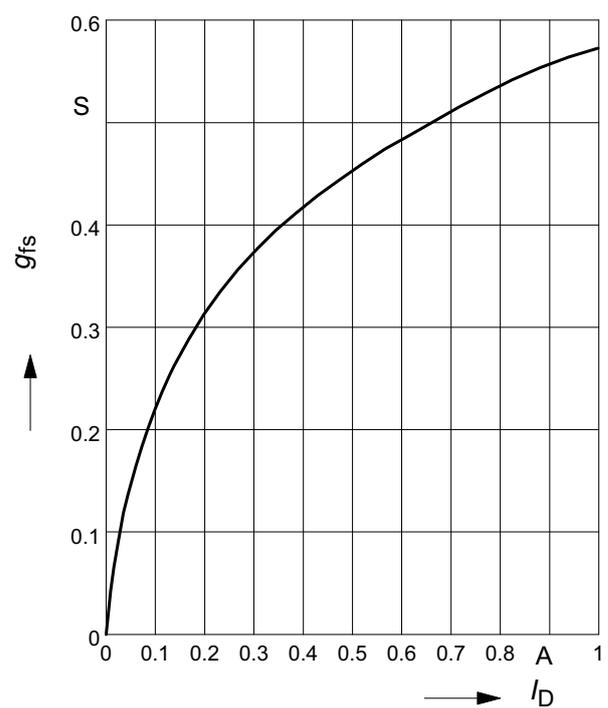
parameter: $T_j = 25\text{ }^\circ\text{C}$



8 Typ. forward transconductance

$$g_{fs} = f(I_D)$$

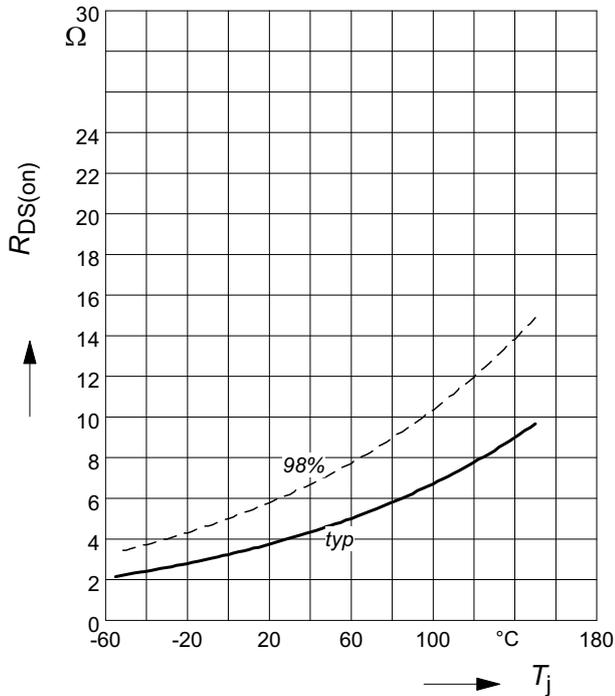
parameter: $T_j = 25\text{ }^\circ\text{C}$



9 Drain-source on-state resistance

$$R_{DS(on)} = f(T_j)$$

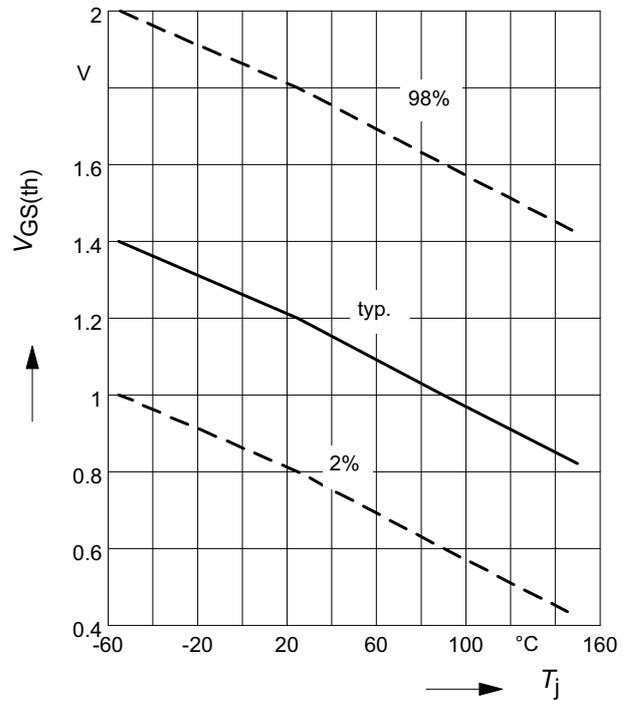
parameter : $I_D = 0.26 \text{ A}$, $V_{GS} = 10 \text{ V}$



10 Typ. gate threshold voltage

$$V_{GS(th)} = f(T_j)$$

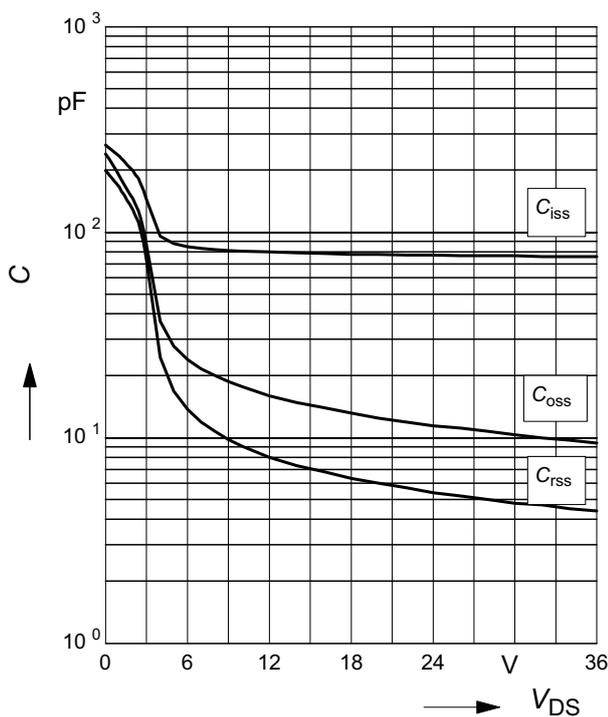
parameter: $V_{GS} = V_{DS}$; $I_D = 108 \mu\text{A}$



11 Typ. capacitances

$$C = f(V_{DS})$$

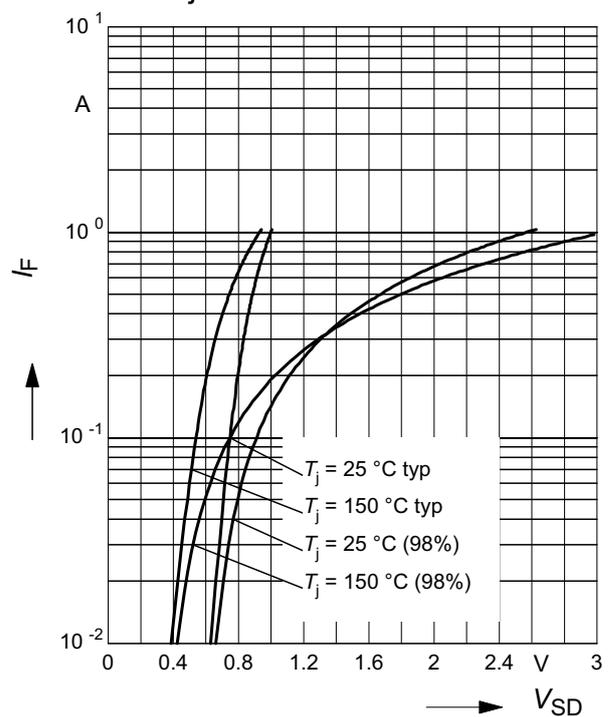
parameter: $V_{GS}=0$, $f=1 \text{ MHz}$, $T_j = 25 \text{ }^\circ\text{C}$



12 Forward character. of reverse diode

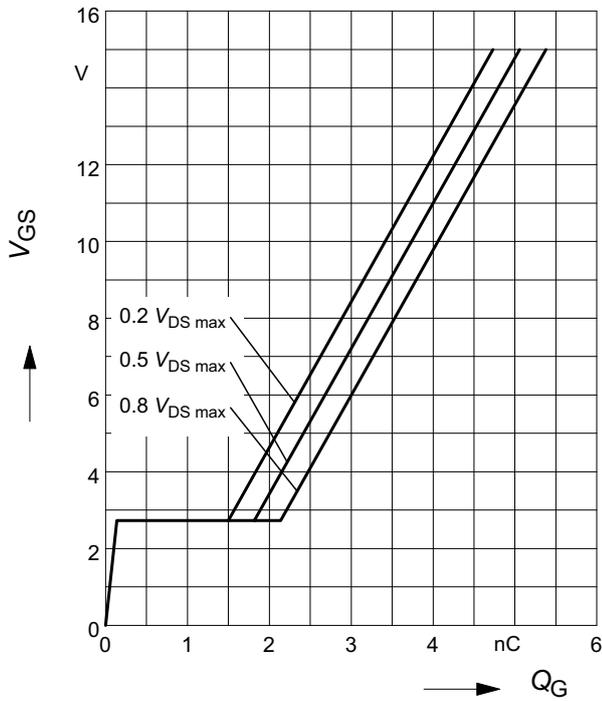
$$I_F = f(V_{SD})$$

parameter: T_j



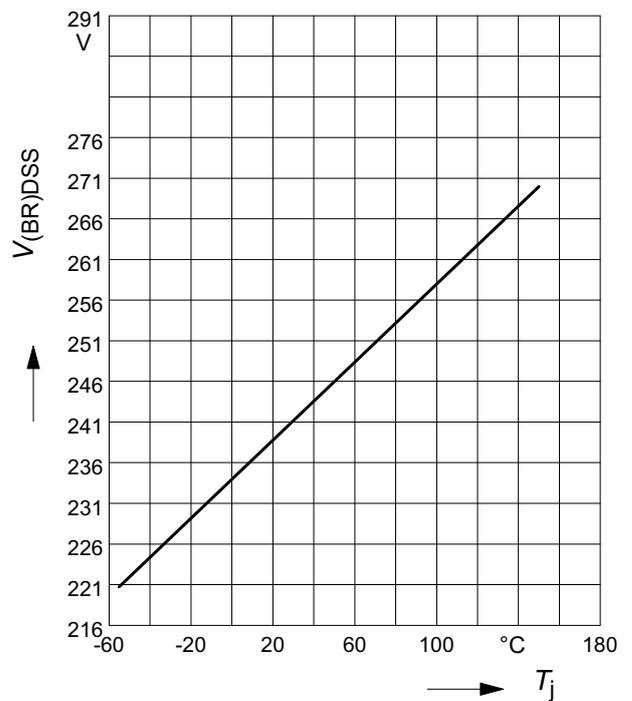
13 Typ. gate charge

$V_{GS} = f(Q_G)$; parameter: V_{DS} ,
 $I_D = 0.26 \text{ A pulsed}$, $T_j = 25 \text{ °C}$

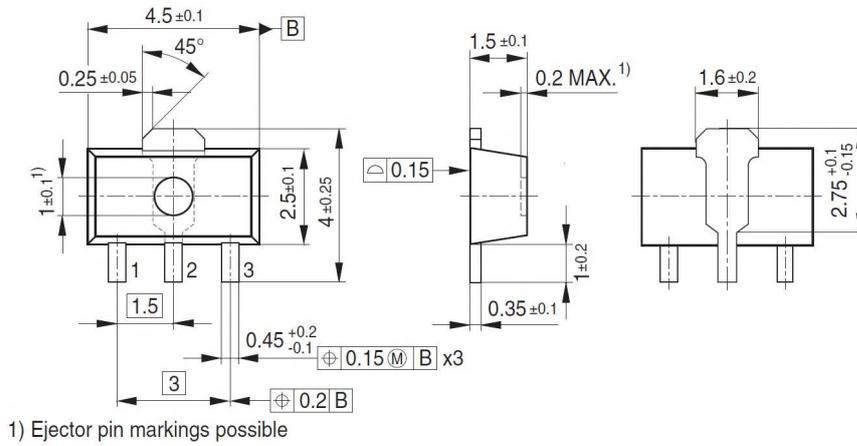


14 Drain-source breakdown voltage

$V_{(BR)DSS} = f(T_j)$

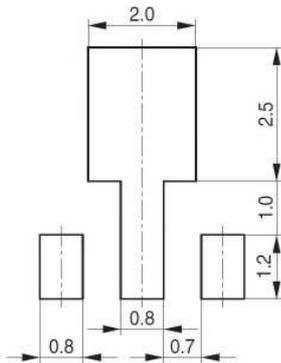


Package Outline SOT-89



Footprint

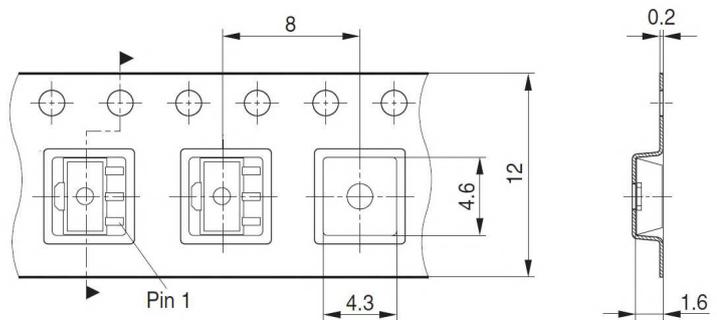
Soldering type: Reflow soldering



Tape and Reel

Reel $\varnothing 180$ mm: 1.000 Pieces/Reel
 Reels/Box: 1 x 1.000 = 1.000

Reel $\varnothing 330$ mm: 4.000 Pieces/Reel
 Reels/Box: 1 x 4.000 = 4.000



Dimensions in mm

Revision History

BSS87

Revision: 2016-06-09, Rev. 2.0

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.0	2016-06-09	Release of final version

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